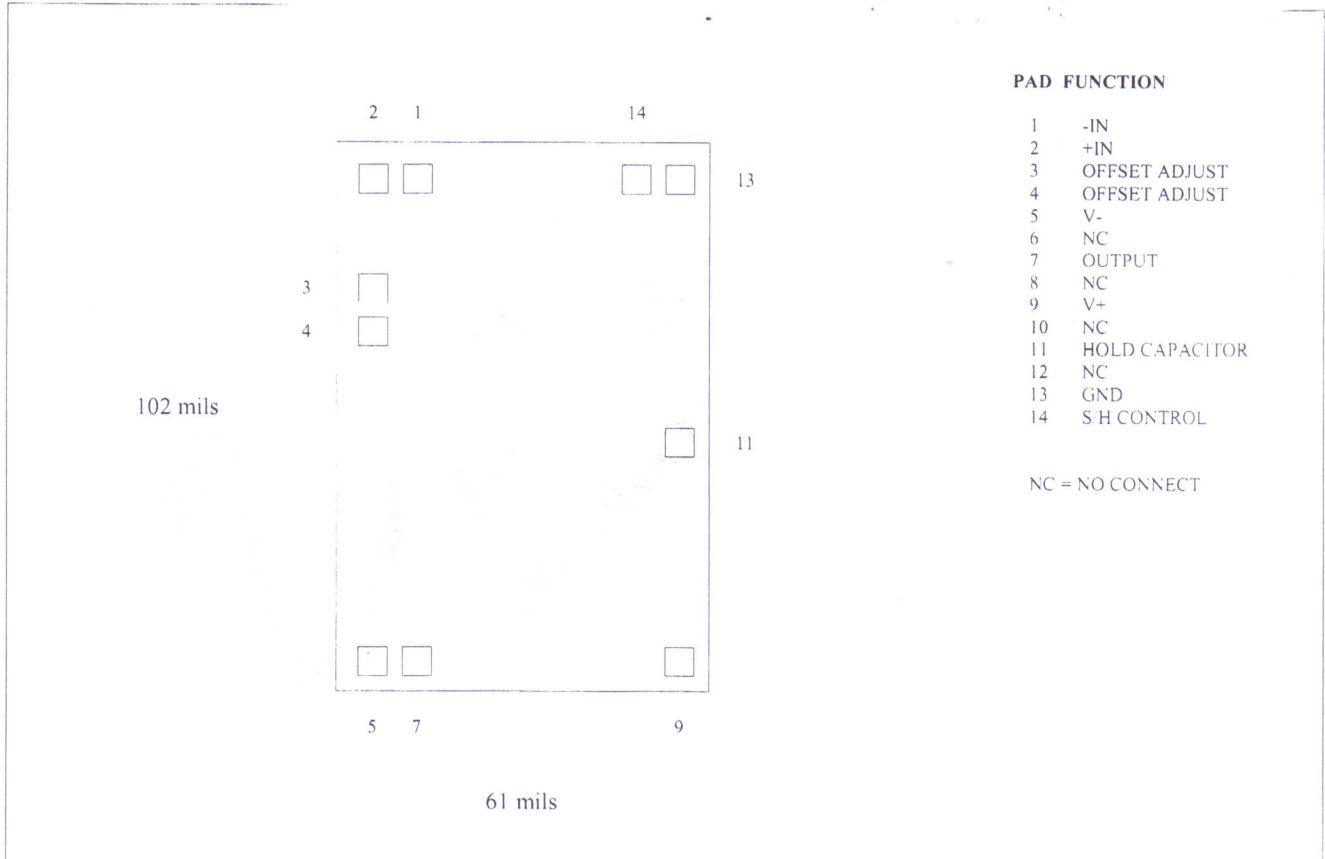




**Sierra Components, Inc.**  
 2222 Park Place • Suite 3E • Minden, Nevada 89423  
 Phone: 775.783.4940 Fax: 775.783.4947



NOTE: Chip back must be connected to V-

The information given is believed to be correct at the time of issue.  
 Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.  
 Chip back potential is the level at which bulk silicon is maintained either by bond pad connection or in some cases the potential to which the chip back must be connected if stated above.

Note: 1 mil = 0.001inch

<p><u>APPROVED</u></p> <p>D Markham</p> <p>DATE: 18/05/01</p>	<p>HA0-2425</p> <p>HARRIS</p>	<p><u>DIE INFORMATION</u></p> <p>DIMENSIONS (Mils): 61 x 102 x 19          BOND PADS (Mils): 4 x 4          MASK. REF:          GEOMETRY:          BACK POTENTIAL: V- (SEE NOTE)</p>
<p><u>SERIAL NUMBER</u></p> <p>002397</p>		<p><u>METALLISATION</u></p> <p>TOP: Al          BACK: Si</p>